PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Diamond Innovations, Inc.	01/20/2011

RECEIVING PARTY DATA

Name:	Ehwa Diamond Industiral Company, Ltd.
Street Address:	520-2 Wondong, Osansi
City:	Kyunggido
State/Country: KOREA, DEMOCRATIC PEOPLE'S REPUBLIC OF	
Postal Code:	447804

PROPERTY NUMBERS Total: 6

Property Type	Number
Patent Number:	7082939
Patent Number:	7089924
Patent Number:	7096863
Patent Number:	7637257
Patent Number:	7814895
Application Number:	12630887

CORRESPONDENCE DATA

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Address Line 4: Worthington, OHIO 43085

ATTORNEY DOCKET NUMBER: EHWA IP TRANSFER

PATENT

REEL: 026067 FRAME: 0020

\$240,00 7082939

NAME OF SUBMITTER:	Maria C. Gasaway
Total Attachments: 6 source=RedactedAgreementforPatentAssignments#page1.tif source=RedactedAgreementforPatentAssignments#page2.tif source=RedactedAgreementforPatentAssignments#page3.tif source=RedactedAgreementforPatentAssignments#page4.tif source=RedactedAgreementforPatentAssignments#page5.tif source=RedactedAgreementforPatentAssignments#page6.tif	

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PATENT ASSIGNMENT AGREEMENT

THIS PATENT ASSIGNMENT AGREEMENT ("Agreement") is made and entered into on this 20 day of January, 2011 by and between Diamond Innovations Inc., a company organized and existing under the laws of the state of Delaware in the United States of America, having its principal place of business at 6325 Huntley Road, Worthington, Ohio 43085 ("Assignor"), and Ehwa Diamond Industrial Co., Ltd., a company organized and existing under the laws of the Republic of Korea, having its principal place of business at 520-2 Wondong, Osansi, Kyunggido, Korea 447804 ("Assignee").

WITNESSETH

WHEREAS, Assignor has developed and owns certain technology related to the Frame Saw and Method, Granite Block and Frame Saw with Support Structure and has filed the Patent Applications thereon, of which some were granted patents and some are still pending, as set forth in Schedule A attached hereto (the "Patents and Patent Applications");

WHEREAS, in accordance with the terms and conditions of this Agreement, Assignor desires to sell, assign, convey and transfer to Assignee all of Assignor's rights, title and interest in the Patents and Patent Applications; and

WHEREAS, Assignee desires to acquire ownership of the Patents and Patent Applications from Assignor.

NOW, THEREFORE, the parties hereto, intending to be legally bound, agree as follows:

Article 1 Assignment

1.1 Assignor hereby sells, assigns, conveys and transfers to Assignee, its successors and assigns, its entire rights, title and interest in and to all of the Patents and Patent Applications, along with its right to sue for past infringement, including all current and future claims and causes of action (the "Assignment").



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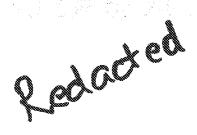
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Article 7 Termination

7.1 This Agreement shall be effective from the date of execution by both parties ("Effective Date") and shall be effective thereafter unless terminated in accordance with this Agreement.



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APPENDIX A

Family #1 - FRAME SAW AND METHOD

Granted:

US 7082939 (10/731,066) issued August 1, 2006 US 7089924; issued August 15, 2006 Chinese Application No. 200380105612.7

Pending:

European Patent Application No. 3812902.9; filed December 10, 2003 Indian Patent Application No.1216/DELNP/2005; filed December 10, 2003 Brazilian Patent Application No. 0316922-7; filed December 10, 2003

Family #2 - GRANITE BLOCK -

Granted:

US 7096863; issued August 29, 2006

Pending:

Chinese Application No. 20040038738; filed December 22, 2004 European Patent Application No. 4815249.0; filed December 22, 2004 Indian Patent Application No. 3342/DELNP/2006; filed December 24, 2004 Brazilian Patent Application No. PI0417328-7; filed December 22, 2004 South Korean Patent Application No. 10-2006-7012729; filed December 22, 2004

Family #3 - FRAME SAW WITH SUPPORT STRUCTURE - 12598

Granted:

Indian Patent Application No. 1379/DELNP/2006 Chinese Application No.200480023359.5 US 7,637,257; issued December 29, 2009 US 7,814,895; issued October 19, 2010

Pending:

US 12/630,887; filed December 4, 2009 – FRAME SAW WITH SUPPORT STRUCTURE AND SPACERS; allowed European Patent Application No. 4781061.9; filed August 13, 2004 Brazilian Patent Application No. PI0413591-1; filed August 13, 2004

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PATENT REEL: 026067 FRAME: 0026

IN WITNESSETH WHEREOF, the Assignor and the Assignee have executed 2 copies of this Agreement, respectively put their names and affixed their seals hereto and shall respectively hold each one copy hereof.

The Assignor

DIAMOND INNOVATIONS INC.

By: Mark Schweizer

Title: President

The Assignee

EHWA DIAMOND INDUSTRIAL CO., LTD.

Name: J. Christine Kim

Title: President

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RECORDED: 04/04/2011